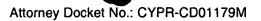
217



> - AUE		PATENT AND TRADEMA				
base of Deposit: 01/29		rument is being deposited with the United State and Trademark Office, Washington, D.C., 20231, RINE RINALDI Signature of the Person Making the Deposit:	es Postal Service in an envelope on the below date of deposit. UMULUU BUNALOW			
In re Application	on of: Kenneth Y. Ogami and Ma	arat Zhaksilikov	·			
Serial No.: 09	9/989,761	Examiner: not yet a	Examiner: not yet assigned			
Filed: 11/19	9/01	Art Unit: 2171	Art Unit: 2171			
For: STORING PROJECTS	G OF GLOBAL PARAMETER DE	EFAULTS AND USING THEM OVER	R TWO OR MORE DESIGN			
Assistant C	ommissioner for Patents	·	RECEIVED			
Washington,	, D.C. 20231		FEB 1 0 2003			
	AM	MENDMENT TRANSMITTAL				
1. Transı	mitted herewith is an amendmer	nt for this application	Technology Center 2100			
	ted herewith is a response to an sheets)	office action for the above identified	d patent application.			
x Transmitt	ed herewith areshe	ets of Red Line drawings.				
2. Applic	ant is other than a small entity					
	Ext	tension of Term				
3. The pr	roceedings herein are for a pate	ent application and the provisions of	37 C.F.R. 1.136 apply.			
(a) []		ension of time under 37 C.F.R. 1.13 or the total number of months check	6 ed below:) E			
	Extension [] one month [] two months [] three months [] four months	Fee \$110.00 \$410.00 \$930.00 \$1,450.00	RECEIVED FEB 13 2003 TECHNOLOGY CENTER 2800 :)			
If an additional	l extension of time is required, p	please consider this a petition therefore	or. 800			
(b) [X]	Applicant believes that no ext being made to provide for the need for a petition for extensi	ension of term is required. Howeve possibility that applicant has inadve on of time.	r, this conditional petition is ertently overlooked the			





Fee Calculation

The fee for claims (37 C.F.R. 1.16(b)-(d)) has been calculated as shown below:

Fee Items	Claims Remaining After Amendment	Highest Number of Claims Previously Paid For	. Present Extra Claims	Fee Rate	Total	
Total Claims	28	- 28 =	0	x \$18.00	\$0.00	
Independent Claims	5	- 5 =	0	x \$84.00	\$0.00	
Multiple Dependent Claim Fee (one or more, first added by this \$260.00 amendment)						
Total Fees						

PAYMENT OF FEES

- 5. The full fee due in connection with this communication is provided as follows:
- The Commissioner is hereby authorized to charge any additional fees associated with this communication or credit any overpayment to Deposit Account No.: 23-0085. A <u>duplicate copy</u> of this authorization is enclosed.
- [] A check in the amount of \$
- [] Charge any fees required or credit any overpayments associated with this filing to Deposit Account No.: 23-0085.

Please direct all correspondence concerning the above-identified application to the following address:

WAGNER, MURABITO & HAO LLP

Two North Market Street, Third Floor San Jose, California 95113 (408) 938-9060

Respectfully submitted,

Date:

Anthony C. Murabito

Reg. No. 35,295

ECHHOLOGY CENTER 2800



#4/PU-A
970001
2/21/0

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

:

Kenneth OGAMI et al.

: GROUP ART UNIT:

SERIAL NO: 09/989,761

:

FILED: NOVEMBER 19, 2001

: EXAMINER:

FOR: STORING OF GLOBAL

PARAMETER DEFAULTS AND USING THEM OVER TWO OR MORE DESIGN PROJECTS

RECEIVED

PRELIMINARY AMENDMENT

FEB 1 0 2003

COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

Technology Center 2100

SIR:

Prior to examination of the above-identified application, consideration of the following Amendments and Remarks is respectfully requested.

IN THE SPECIFICATION

Please replace the paragraph beginning at page 2, line 5 with the following:

US Patent Application Serial No. 10/033,027, entitled "PROGRAMMABLE MICROCONTROLLER ARCHITECTURE," having docket number CYPR-CD00232, filed on 10/22/2001, and with inventor Warren Snyder is hereby incorporated by reference.

Please replace the paragraph beginning at page 11, line 14 with the following:

In one embodiment, the system 100 is configured to support programmable microcontroller design. In yet another embodiment, the system 100 supports general chip design.